

# 8mΩ 650V D³GaN™ Power FET

V08TC065S1X11

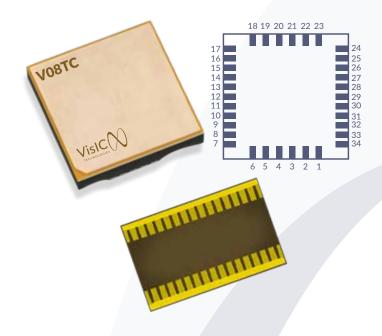
### **Description**

The D³GaN™ (Direct Drive D-Mode) V08TC065S1X11 Power Switch integrates a patented, high-density, lateral GaN power transistor, into a Normally-Off product with extremely low R<sub>DS</sub>(ON) and exceptionally efficient switching performance. The D³GaN™ technology has been implemented into an Isolated High Power SMD package, an innovation by VislC Technologies, very effective in applications requiring High Power and Efficiency, with Low Volume and Cost.

The integrated safety functions ensure safe operation during system start up and shutdown, while having no impact on the switching performance of the GaN transistor.

### **Key features**

- Ultra-fast switching
- Kelvin connection
- Normally-Off
- High power density
- Fully isolated package (3.5KV)
- High Threshold Voltage
- Driven by standard 15V MOSFET driver
- Top cooling
- Package Size 21x23x3mm
- \* GaN die/wafer purchase is possible; please contact us.



## **Applications**

- Solar Inverter
- AC-DC Power Supply
- AC motor
- Battery charger
- Automotive
- Laser driver

#### **Key Performance Parameters**

Parameter	Value
V <sub>DS</sub> (V)	650
$R_{DS}$ (on) (m $\Omega$ )	8
Q <sub>G</sub> (nC)	110
I <sub>D,pulse</sub> (A)	380
I <sub>D</sub> (A)	180



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Maximum	ratings (Tc =	25°C ւ	unless othe	erwise sp	ecified)	
Parameter	Symbol	Values				
		Min	Typical	Max	Unit	Conditions
Continuous drain current	I <sub>D</sub>	-	-	200 145	А	T <sub>C</sub> =25°C T <sub>C</sub> =100°C
Pulsed drain current <sup>1)</sup>	I <sub>D,pulse</sub>	-	-	380	А	
Gate source voltage <sup>2)</sup>	V <sub>GS</sub>	-25	-	+6	V	
Power dissipation	P <sub>TOT</sub>	-	-	500	W	
Operating and storage temperature	T <sub>j</sub> ,T <sub>stg</sub>	-55	-	+150	°C	
	T <sub>C</sub>	-	-	+150		
Continuous reverse current	Is	-	-	200	А	
Reverse pulse current <sup>1)</sup>	I <sub>s,pulse</sub>	-	-	380	А	
	Thermal	charac	teristics			
Parameter	Symbol	Values		I I sa i t	Conditions	
		Min	Typical	Max	Unit	Conditions
Thermal resistance, junction - case	R <sub>θJC</sub>	-	-	0.1	°C/W	Junction to top thermal pad
Thermal resistance, junction - ambient	$R_{\theta JA}$	-	-	65	°C/W	
Soldering peak temperature	T <sub>sold</sub>	-	-	260	°C	from case for 10s
Time within 5°C from peak soldering temperature	tc			30	S	

- 1) Duty cycle =10% and pulse width limited by Tjmax
- 2) See Typical Operating Circuit, VGS defined between terminals 3&4

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